ASSOCIATION CONNECTED ELECTRONICS INDUST	Material Comp © Copyright 2005. Il international and Par	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Form Type Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				rials and M	ials and Mfg Information				
Supplier Info									,			J			
Company name*			Company unique ID			τ	Unique ID Authority				Respon	Response Date*			
onsemi										2024-04	2024-04-10				
Contact Name		Title - Contact			1	Phone - Contact*				Email -	Email - Contact*				
Product-Env-Ste	wards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative			1	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Reque	Requester Item Number Mfr Item		m Number Mfr Item Name				Effective Date	fective Date		Manufacturing Site		Weight*	UOM	Unit Type	
		NTMJS2D5N06CLT T6 60V LL LFPAK WG		K		2024-04-10		1	РВВ		99.445	mg	Each		
Ianufacturin	g Proccess Informa	tion													
Terminal Plating / Grid Array Material T			Cerminal Base Alloy J-STD-020 MSI		L Rating	Peak Prod	Peak Process Body Temperature Max Time at Pe		k Tempera	ture Numb	per of Reflow Cyc	les			
Matte Tin (Sn) - annealed			CU Alloy 1			260	260 C 30		seconds 3						
omments															
vel 1 - maximur	n time at peak temperatu	re during sol	dering is 10-3	0 seconds											
or more inform	ation regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and cornect to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to su											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	6.9	mg	Supplier	Iron (Fe)	7439-89-6		0.0083	mg
			Supplier	Copper (Cu)	7440-50-8		6.8896	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0021	mg
Die	1.1	mg	Supplier	Silicon (Si)	7440-21-3		1.1	mg
Lead Frame	36.7	mg	Supplier	Silver (Ag)	7440-22-4		0.0037	mg
			Supplier	Iron (Fe)	7439-89-6		0.044	mg
			Supplier	Copper (Cu)	7440-50-8		36.6413	mg
			Supplier	Phosphorus (P)	7723-14-0		0.011	mg
Mold Compound-Black	41.4	mg	Supplier	Trimethoxysilylpropanethiol	4420-74-0		0.207	mg
			Supplier	Boron zinc hydroxide oxide	138265-88-0		6.21	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		6.21	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1035	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		26.3925	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.277	mg
Plating	6.3	mg	Supplier	Tin (Sn)	7440-31-5		6.3	mg
Solder Paste	7.0	mg	Supplier	Silver (Ag)	7440-22-4		0.175	mg
			A	Lead (Pb)	7439-92-1	7a	6.475	mg
			Supplier	Tin (Sn)	7440-31-5		0.35	mg
Wire Bond - Cu	0.045	mg	Supplier	Copper (Cu)	7440-50-8		0.045	mg